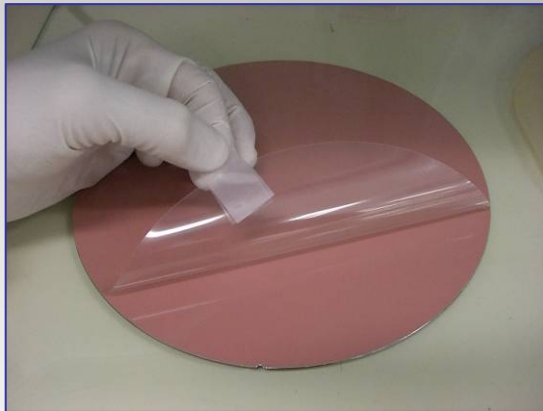


Cleaning Wafer for "Front End"

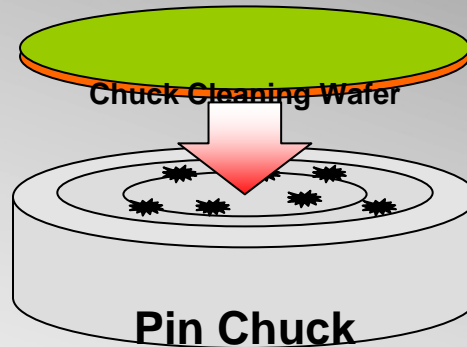


Remove protective front liner before use.

Load wafer with polymer side down into FOUP

Temperature Range
-50C to +200C

Wafer collects debris and materials from each wafer handler arm as well as ejector pins



Vacuum hold on the chuck deforms the compliant polymer around features to capture small and large particles from the pins and wafer chuck surface.

